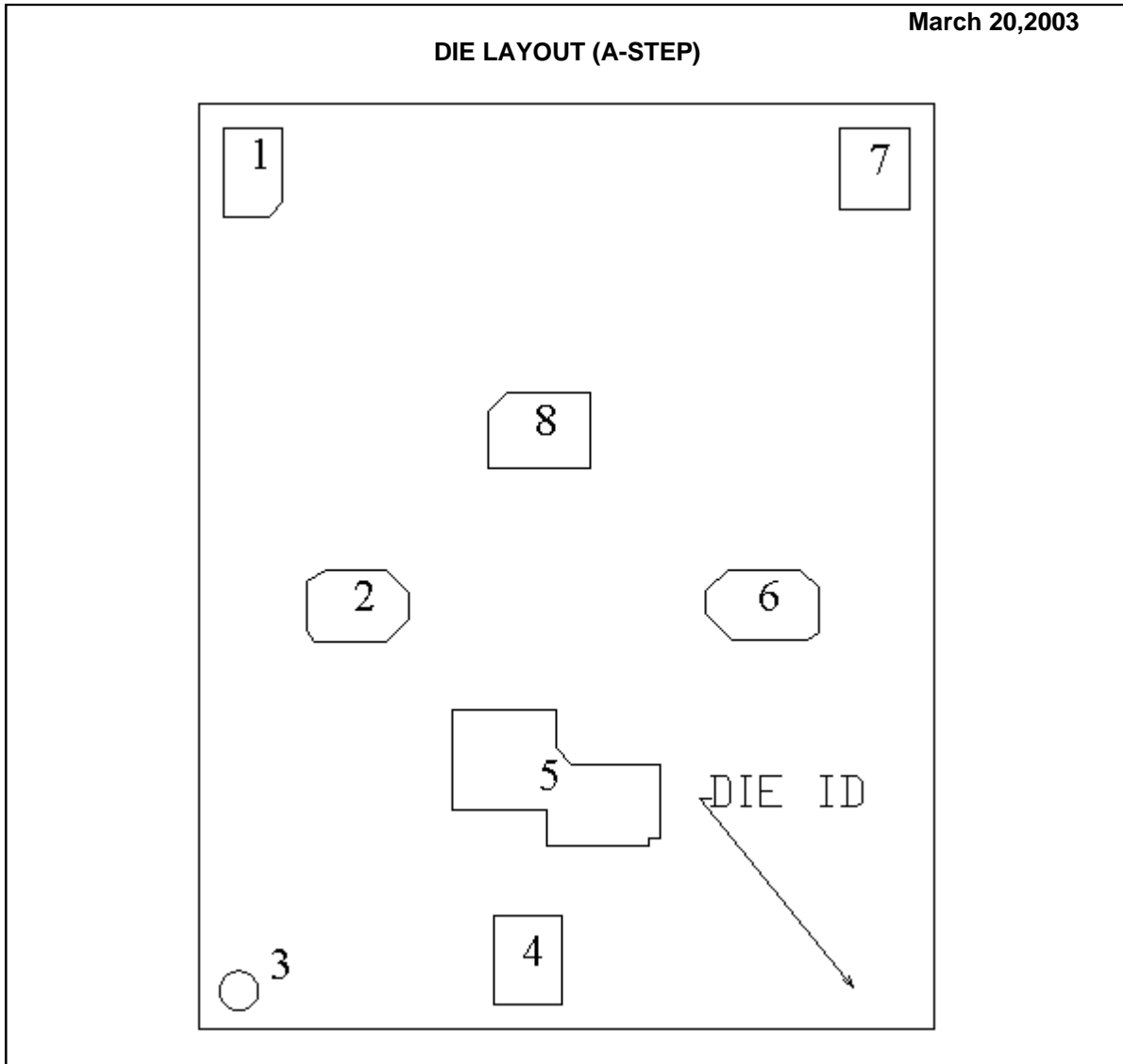


LM338 MDC MWC
5 AMP ADJUSTABLE REGULATOR



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	138A	Bond Pad Opening Size (min)	193 μ m x 295 μ m
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Gold
Die Size (Drawn)	2438 μ m x 3073 μ m 96.0mils x 121.0mils	Back Side Connection	OUTPUT
Thickness	254 μ m Nominal		
Min Pitch	607 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

LM338 MDC MWC
5 AMP ADJUSTABLE REGULATOR

Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
ADJ	1	-1041	1308	193	x	295
OUTPUT	2	-690	-130	338	x	239
NC	3	-1092	-1410	122	x	122
OUTPUT	4	-131	-1308	226	x	295
VIN	5	-32	-701	688	x	452
OUTPUT	6	648	-127	371	x	234
OUTPUT	7	1022	1321	231	x	269
VIN	8	-91	451	335	x	246

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